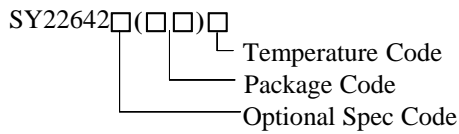


## General Description

SY22642A1/B1 is a linear LED driver for HV TRIAC with integrated 500V power MOSFET and 700V bleeder MOSFET. It uses special technology to achieve high PF and efficiency performance. Special logic functions are added to achieve good compatibility with TRIAC dimmer.

## Ordering Information



Ordering Number	Package type	Note
SY22642A1FCC	SO8E	----
SY22642B1FCC	SO8E	

## Features

- Compatible with HV TRIAC Dimmer
- Integrated: 500V Main MOS and 700V Bleeder MOS
- Latching Current is Adjustable
- Special Low Power Loss Control
- High PF: PF>0.7
- No Magnetic Components and Support All Components Surface Mounted
- Compatible with Brazil 60Hz
- RoHS Compliant and Halogen Free
- Compact Package: SO8E

## Applications

- LED Lighting

Part Number	Minimum output current
SY22642A1	>16mA
SY22642B1	>12mA

## Typical Applications

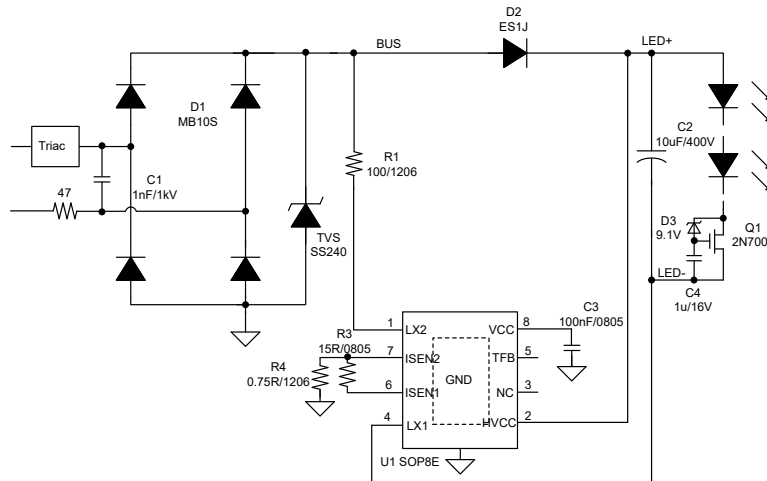
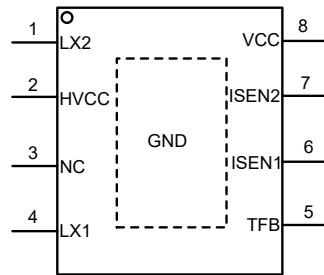


Figure.1 Typical application

## Pinout (top view)



(SO8E)

Part Number	Package type	Top Mark <sup>Ⓞ</sup>
SY22642A1FCC	SO8E	<b>DBGxyz</b>
SY22642B1FCC	SO8E	<b>DMNxyz</b>

Note ①: x=year code, y=week code, z=lot number code

Pin Name	Pin number	Pin Description
LX2	1	Drain of Bleeding MOS pin.
HVCC	2	HV power supply pin.
NC	3	No connect.
LX1	4	Drain of Main MOS pin.
TFB	5	Thermal fold back setting pin.
ISEN1	6	Main MOS Current Sense Pin. The output current is decided by $I_{OUT} = \frac{V_{REF}}{R_{ISEN1} + R_{ISEN2}}$
ISEN2	7	BLD MOS Current Sense Pin. Latching current is adjusted by R <sub>ISEN2</sub> . Recommended value: R <sub>ISEN2</sub> > 0.7 ohm.
VCC	8	Power supply pin.
GND	9	Ground.

## Block Diagram

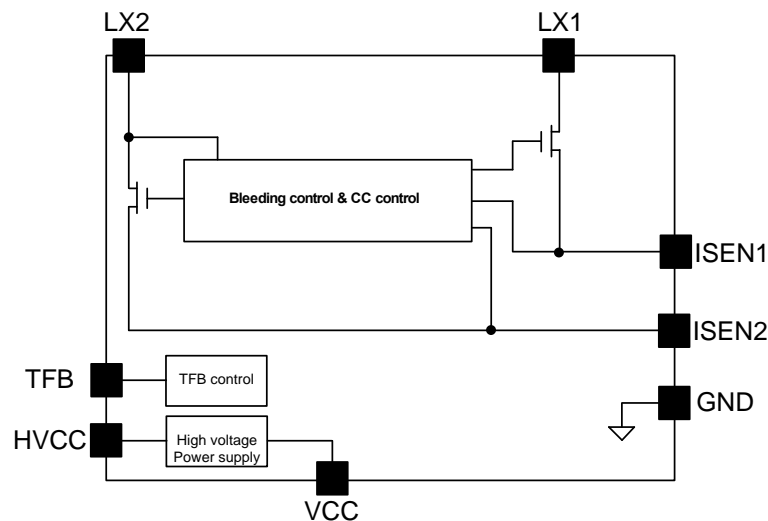


Fig.3 Block Diagram



**SILERGY**

# SY22642A1/B1

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## Absolute Maximum Ratings (Note 1)

LX2, HVCC	-----	-0.3V~700V
LX1	-----	-0.3V~500V
TFB, ISEN1, ISEN2	-----	-0.3V~3.6V
VCC	-----	-0.3~ 22V
Power Dissipation, @ T <sub>A</sub> = 25°C SO8E	-----	3.3W
Package Thermal Resistance (Note 2)		
SO8E, θ <sub>JA</sub>	-----	30°C/W
SO8E, θ <sub>JC</sub>	-----	10°C/W
Junction Temperature Range	-----	-40°C to 150°C
Lead Temperature (Soldering, 10 sec.)	-----	260°C
Storage Temperature Range	-----	-65°C to 150°C

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## Recommended Operating Conditions (Note 3)

Junction Temperature Range	-----	-40°C to 150°C
Ambient Temperature Range	-----	-40°C to 120°C

## Electrical Characteristics

( $V_{IN} = 15V$  (Note 3),  $T_A = 25^\circ C$  unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Power Supply Section</b>						
VIN Turn-on Threshold	$V_{VIN\_ON}$		11	12.1	13.2	V
VIN Turn-off Threshold	$V_{VIN\_OFF}$		7.8	8.8	9.8	V
Quiescent Current	$I_Q$		210	280	350	$\mu A$
<b>Error Amplifier Section</b>						
Internal Reference Voltage	$V_{REF}$		0.291	0.3	0.309	V
<b>MOS Section</b>						
Clamped Current of LX1 MOS	$I_{CLP}$			32		mA
BV of LX1 MOS	$V_{BV\_LX1}$		500			V
BV of LX2 MOS	$V_{BV\_LX2}$		700			V
<b>Thermal Section</b>						
Minimum Thermal Foldback Temperature	$T_{FB1}$			115		$^\circ C$
Maximum Thermal Foldback Temperature	$T_{FB2}$			155		$^\circ C$

**Note 1:** Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Note 2:**  $\Theta_{JA}$  is measured in the natural convection at  $T_A = 25^\circ C$  on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard. Test condition: Device mounted on 2” x 2” FR-4 substrate PCB, 2oz copper, with minimum recommended pad on top layer and thermal vias to bottom layer ground plane.

**Note 3:** Increase VIN pin voltage gradually higher than  $V_{VIN\_ON}$  voltage then turn down to 12V.

## Operation

SY22642A1/B1 is a HV TRIAC Linear Controller. It recognizes ac mode, leading edge mode, trailing edge mode automatically in first sixteen ac cycles.

For improving the efficiency, the current of LX1 is compensated by VBUS. In the peak voltage of VBUS, the current of LX1 is the smallest, and then the loss is decreased.

In leading edge mode, SY22642A1/B1 controls the fire current automatically which is the Silergy exclusive patent.

For trailing edge dimmer, SY22642A1/B1 has a good performance by Reliable reset control.

TFB is available to be set for different application.

PF is higher than 0.7 suitable for European market.

## Applications Information

### AC Mode

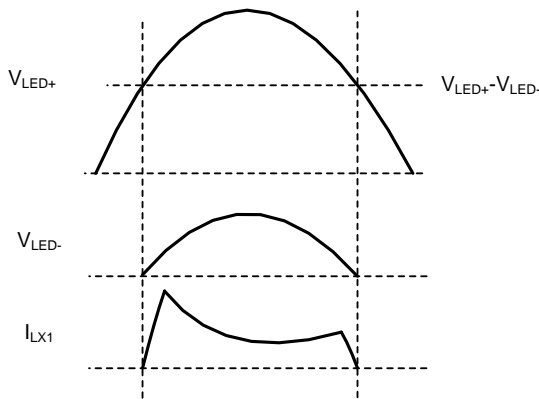


Fig.4 state in ac mode

In ac mode, the wave is showed above. The current of LX1 is compensated by VBUS for good efficiency performance.

In any kinds of mode, the output current is regulated by ISEN1 and ISEN2.

$$I_{OUT} = \frac{V_{REF}}{R_{ISEN1} + R_{ISEN2}}$$

### Trailing Edge Mode

In trailing edge mode, SY22642A1/B1 tries to reset the dimmer when the current of LX1 MOS is off. As showed below.

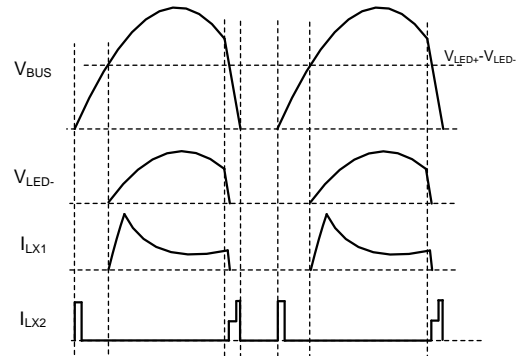


Fig.5 state in trailing edge mode

### Trailing Edge Mode

In trailing edge mode, the fire current is decided by the resistor of ISEN2.

With smaller  $R_{ISEN2}$ , the latching current of LX2 is larger. For improving the efficiency, recommend to choose larger value of  $R_{ISEN2}$ , and satisfy appropriate compatibility.

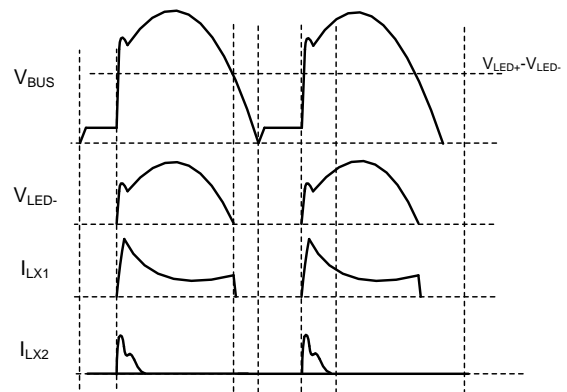
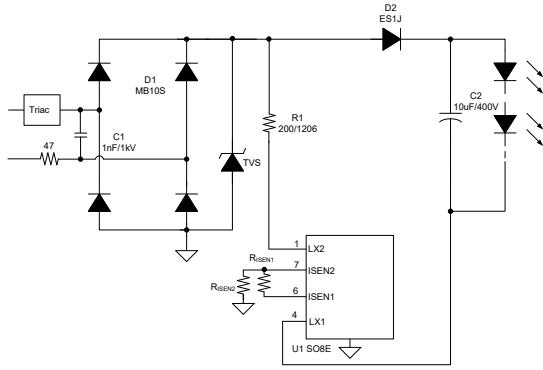


Fig.6 state in leading edge mode

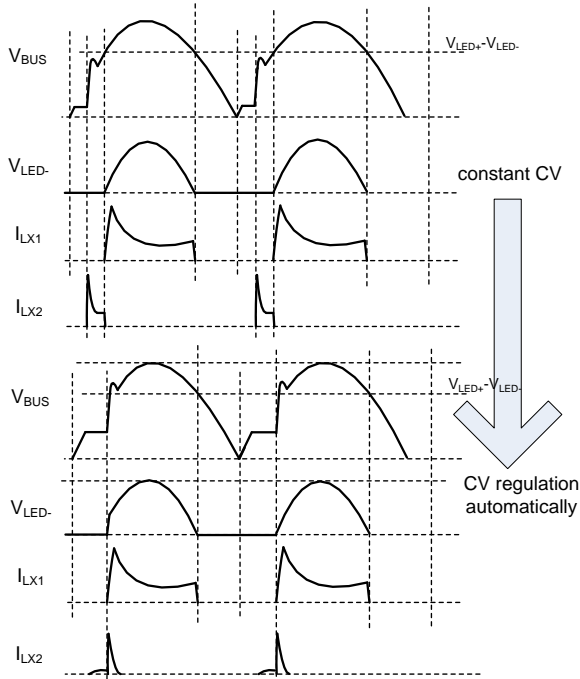
The current of LX1 and LX2 flow through  $R_{ISEN2}$  simultaneously. So the actual fire current contains both two currents which help to decrease the fire loss. Recommend value:  $R_{ISEN1} > 0.7 \text{ ohm}$ .



**Fig.6 fire current sample resistor**

### CV Logic

For further improve efficiency, SY22642A1/B1 integrate automatic CV regulation logic. So the loss caused by holding current is reduced.



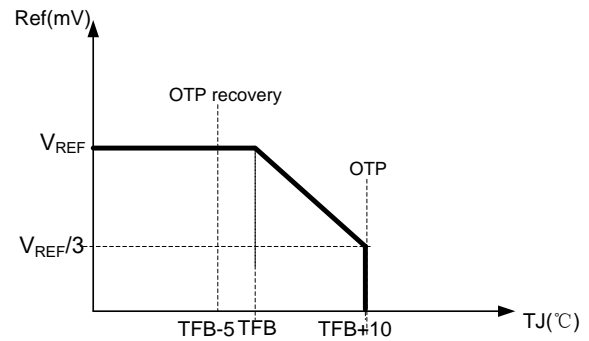
**Fig.7 CV logic**

### TFB setting

TFB is set by TFB pin and controlled by digital logic. So please do not select the value out of list.

RTFB(k ohm)	TFB(°)
NC	155
120	150
56	145
30	140
15	135
7.5	130
3.6	125
1.8	120
0	115

TFB curve is showed as below.



**Fig.8 TFB curve**

## Design Example

A design example of typical application is shown below step by step.

### Example A

#1. Identify design specification

Target parameter			
$I_{OUT}$	22mA	$T_{TFB}$	150°

#1. Set  $R_{ISEN1}$  and  $R_{ISEN2}$

Set  $R_{ISEN2}=0.75\text{ ohm}$

$$R_{ISEN1} = \frac{V_{REF}}{I_{OUT}} - R_{ISEN2} = \frac{0.3}{0.022} - 0.75 \approx 13\text{ ohm}$$

#2 set TFB pin

$R_{TFB}=NC$ .

#3 final result

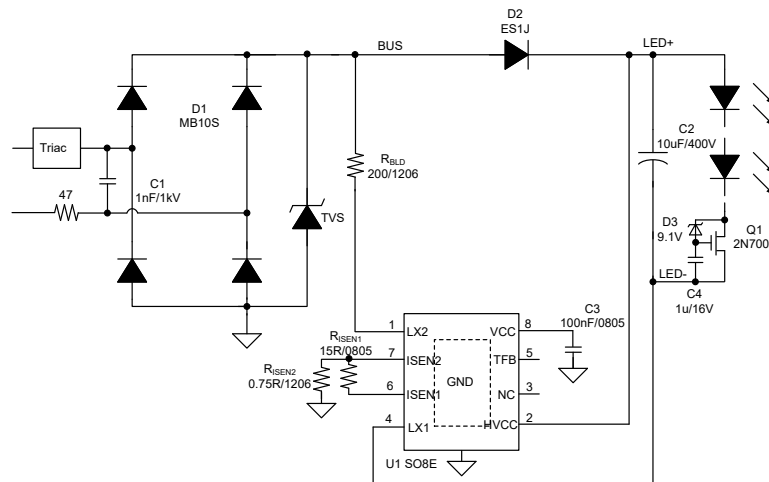
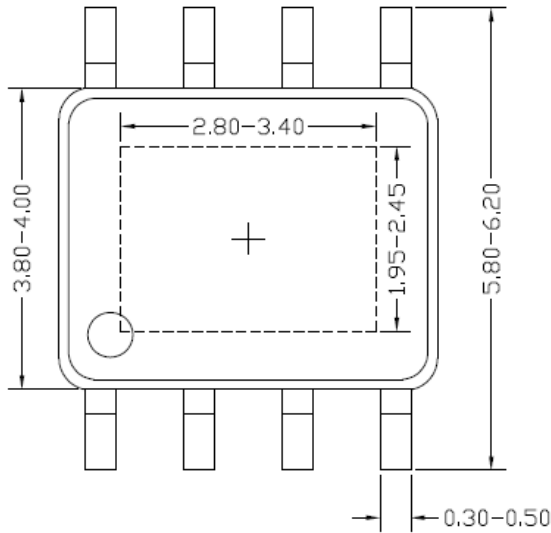
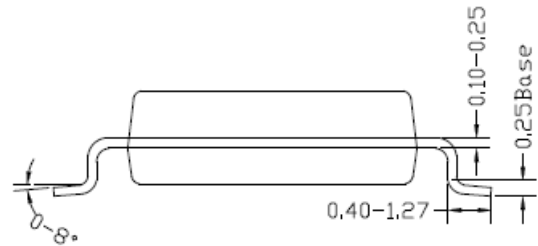


Fig.9 Final Design Result

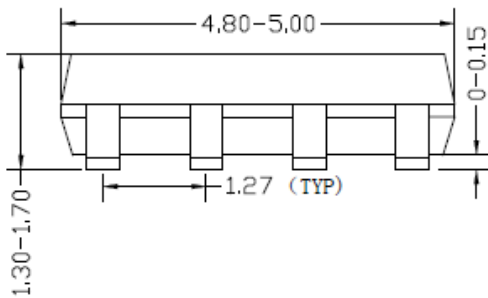
## SO8E Package Outline & PCB layout



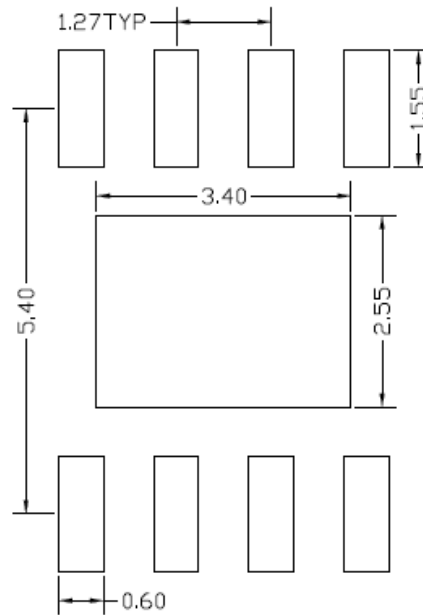
Top view



Side view



Front view



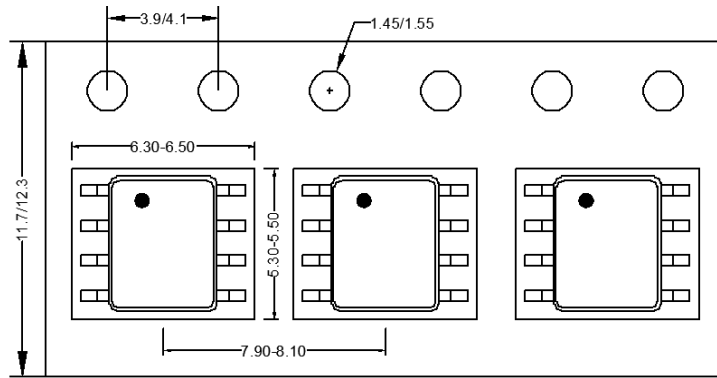
Recommended PCB Layout  
(Reference Only)

**Notes: All dimension in millimeter and exclude mold flash & metal burr.**

**Taping & Reel Specification**

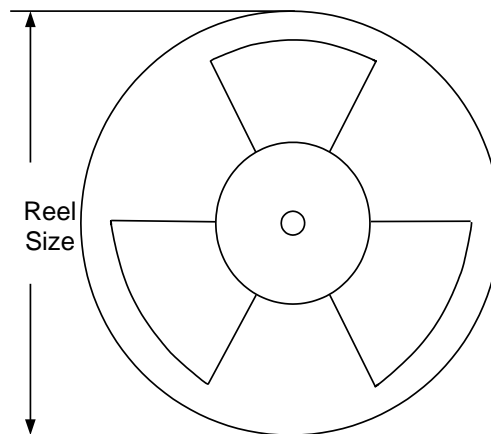
**1. Taping orientation**

**SO8E**



**Feeding direction** →

**2. Carrier Tape & Reel specification for packages**



Package types	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer * length(mm)	Leader * length (mm)	Qty per reel (pcs)
SO8E	12	8	13"	400	400	2500

**Others: NA**